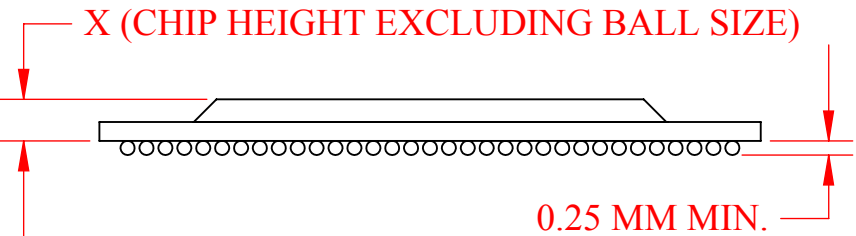


REVISIONS			
REV.	DESCRIPTION	DATE	APPROVED
A	NEW RELEASE	9/26/05	FWANG
B	ECN#705211: UPDATED PAD SIZE AND CLIP	7/21/07	FWANG
C	PER ECN#005051	05/06/10	FWANG

NOTES:

1. SEE TABLE BELOW FOR COMPLETE PART NUMBER WITH OPTIONS.
2. RECOMMENDED KEEP-OUT AREA: 38X38 MM.
3. COLOR OF CLIP TO BE SELECTED BASED ON CHIP HEIGHT AS ILLUSTRATED BELOW.
4. CLIP FITS MIN. 0.25 MM SOLDER BALL HEIGHT.



X	CLIP COLOR
3.3 ±0.3 MM	YELLOW
1.7 ±0.3 MM	BLUE
0.9 ±0.3 MM	ORANGE

COMPLETE PART NUMBER WITH OPTIONS

ROOT	HEIGHT (hh)	MATERIAL (m)	BASE	CLIP (c)	PAD
INM33002-	12 (11.6 MM)	P (ALUMINUM)	/2.6 (2.6 MM)	Y (YELLOW)	+T710
	15 (14.6 MM)			BU (BLUE)	
	20 (19.6 MM)	PCU (COPPER)		O (ORANGE)	+OTHER
	25 (24.6 MM)			K33	

EXAMPLE PART NUMBER: INM33002-20PCU/2.6BU+T710

ITEM NO.	PART NUMBER	DESCRIPTION	QTY.
1	INM33002-hhm/2.6	ROUND PIN HEAT SINK (SEE TABLE ON THE RIGHT FOR HEIGHT CODE hh & m)	1
2	BCP35-09(33)c	33 MM EZ-SNAP CLIP (SEE TABLE ON THE RIGHT FOR CLIP CODE c)	1
3	OPTIONAL	THERMAL PAD (31X31 MM OR FULL COVERAGE OF HEAT SINK BASE)	1

NEXT ASSY	USED ON

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MM TOLERANCES ARE:		CAD GENERATED DRAWING, DO NOT MANUALLY UPDATE	
		APPROVALS	DATE
DECIMALS	ANGLES	DRAWN	
X. ± .25	± 1°	FWANG	9/26/05
X.X ± .25		CHECKED	
X.XX ± .10		TSIN	9/28/05
MATERIAL	RESP ENG	FWANG	9/26/05
		MFG ENG	
FINISH	QUAL ENG		
DO NOT SCALE DRAWING			

RADIAN HEATSINKS
DIV. OF INTRICAST CO. INC.
2160 WALSH AVE
SANTA CLARA, CA - 95050

33 MM ROUND PIN HEAT SINK

SIZE	DWG. NO.
B	

INM33002

REV.
C